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Amendments to the Specification: Please replace Paragraph [0036] with the following replacement paragraph:

[0036] As shown in FIG. 7, after the opening is formed, the metal (preferably copper) which is used to form the redistribution conductor ~~211~~ 221 is electroplated onto the exposed portion of the metallization **209**. The photoresist is then stripped, and the exposed metallization **209** is removed with an appropriate etch as shown in FIG. 8. For example, if the metallization **209** comprises a conductive release layer **211** of TiW and a conductive seed layer **213** of copper, the conductive seed layer **213** may be removed with a chlorite or persulfate copper etchant using a spray acid tool or, alternatively, in an agitated bath, and the conductive release layer **211** may be removed with a hot hydrogen peroxide solution. Preferably, the conductive release layer **211** and the conductive seed layer **213** are sufficiently thin that the exposed portions of these layers are removed after only brief exposure to these etchants. Moreover, it is preferred that the redistribution conductor **221** is sufficiently thick compared to the conductive release layer **211** and the conductive seed layer **213** that its dimensions are substantially unaltered by the etchants used to remove the exposed portions of these layers. As indicated in FIG. 10, etching of the conductive release layer **211** and the conductive seed layer **213** may result in a

slight amount of undercutting underneath the redistribution conductor **221** and the bump contact **231** (see FIG. 10).